



Product Change Notification - GBNG-06YWZH104

Date:

28 Nov 2017

Product Category:

Memory; Switching Regulators; Successive Approximation Register (SAR) A/D Converters; Linear Op Amps; Linear Comparators; Linear Selectable Gain Amplifiers; Linear Programmable Gain Amplifiers

Notification subject:

CCB 3177 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 120K and 121K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Notification text:**PCN Status:**

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of the 120K and 121K wafer technologies available in 8L MSOP package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at MTAI assembly site.

Post Change:

Assembled at MTAI or MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand – Branch (MMT)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	8390A	8390A	8390A
Molding compound material	G600V	G600V	G600V
Lead frame material	CDA194	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site.



Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2017					-->	January 2018				
Workweek	44	45	46	47	48		01	02	03	04	05
Initial PCN Issue Date					X						
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

November 28, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_GBNG-06YWZH104_Affected CPN.pdf](#)
- [PCN_GBNG-06YWZH104_Qual Plan.pdf](#)
- [PCN_GBNG-06YWZH104_Affected CPN.xlsx](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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To opt out of future offer or information emails (other than product change notification emails), click here to go to **microchipDIRECT** and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's



products or services."

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Affected Catalog Part Numbers (CPN)

PCN_GBNG-06YWZH104
CATALOG_PART_NBR
24AA04-I/MSRVC
24AA04T-I/MSRVC
24C02C-E/MS
24C02C-I/MS
24C02CT-E/MS
24C02CT-I/MS
24LC01B-I/MS
24LC01BT-I/MS
24LC04B-I/MSRVC
24LC04BT-I/MSRVC
MCP1650R-E/MS
MCP1650RT-E/MS
MCP1650S-E/MS
MCP1650ST-E/MS
MCP1651R-E/MS
MCP1651RT-E/MS
MCP1651S-E/MS
MCP1651ST-E/MS
MCP1652R-E/MS
MCP1652RT-E/MS
MCP1652S-E/MS
MCP1652ST-E/MS
MCP3001-I/MS
MCP3002-I/MS
MCP3201-CI/MS
MCP3201T-CI/MS
MCP3202-CI/MS
MCP3202T-CI/MS
MCP3301-BI/MS
MCP3301-CI/MS
MCP3301T-BI/MS
MCP3301T-CI/MS
MCP6002-E/MS
MCP6002-I/MS
MCP6002T-E/MS
MCP6002T-E/MSHAZ
MCP6002T-I/MS
MCP6021-E/MS
MCP6021T-E/MS
MCP6031-E/MS
MCP6031T-E/MS
MCP6032-E/MS
MCP6032T-E/MS

GBNG-06YWZHI04 - CCB 3177 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 120K and 121K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06YWZHI04
CATALOG_PART_NBR
MCP6033-E/MS
MCP6033T-E/MS
MCP6041-E/MS
MCP6041-I/MS
MCP6041T-E/MS
MCP6041T-I/MS
MCP6042-E/MS
MCP6042-I/MS
MCP6042T-E/MS
MCP6042T-I/MS
MCP6043-E/MS
MCP6043-I/MS
MCP6043T-E/MS
MCP6043T-I/MS
MCP6141-E/MS
MCP6141-I/MS
MCP6141T-E/MS
MCP6141T-I/MS
MCP6142-E/MS
MCP6142-I/MS
MCP6142T-E/MS
MCP6142T-I/MS
MCP6143-E/MS
MCP6143-I/MS
MCP6143T-E/MS
MCP6143T-I/MS
MCP616-I/MS
MCP616T-I/MS
MCP617-I/MS
MCP617T-I/MS
MCP618-I/MS
MCP618T-I/MS
MCP6231-E/MS
MCP6231T-E/MS
MCP6232-E/MS
MCP6232T-E/MS
MCP6241-E/MS
MCP6241T-E/MS
MCP6242-E/MS
MCP6242T-E/MS
MCP6271-E/MS
MCP6271T-E/MS
MCP6272-E/MS

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Affected Catalog Part Numbers (CPN)

PCN_GBNG-06YWZH104
CATALOG_PART_NBR
MCP6272T-E/MS
MCP6273-E/MS
MCP6273T-E/MS
MCP6275-E/MS
MCP6275T-E/MS
MCP6281-E/MS
MCP6281T-E/MS
MCP6282-E/MS
MCP6282T-E/MS
MCP6283-E/MS
MCP6283T-E/MS
MCP6285-E/MS
MCP6285T-E/MS
MCP6291-E/MS
MCP6291T-E/MS
MCP6292-E/MS
MCP6292-E/MSAAA
MCP6292T-E/MS
MCP6292T-E/MSAAA
MCP6293-E/MS
MCP6293T-E/MS
MCP6295-E/MS
MCP6295T-E/MS
MCP6442-E/MS
MCP6442T-E/MS
MCP6541-E/MS
MCP6541-I/MS
MCP6541T-E/MS
MCP6541T-I/MS
MCP6542-E/MS
MCP6542-I/MS
MCP6542T-E/MS
MCP6542T-I/MS
MCP6543-E/MS
MCP6543-I/MS
MCP6543T-E/MS
MCP6543T-I/MS
MCP6546-E/MS
MCP6546-I/MS
MCP6546T-E/MS
MCP6546T-I/MS
MCP6547-E/MS
MCP6547-I/MS

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Affected Catalog Part Numbers (CPN)

PCN_GBNG-06YWZHZH104
CATALOG_PART_NBR
MCP6547T-E/MS
MCP6547T-I/MS
MCP6548-E/MS
MCP6548-I/MS
MCP6548T-E/MS
MCP6548T-I/MS
MCP6G01-E/MS
MCP6G01T-E/MS
MCP6G02-E/MS
MCP6G02T-E/MS
MCP6G03-E/MS
MCP6G03T-E/MS
MCP6L02T-E/MS
MCP6L1T-E/MS
MCP6L2T-E/MS
MCP6L71T-E/MS
MCP6L72T-E/MS
MCP6L91T-E/MS
MCP6L92T-E/MS
MCP6L92T-E/MSHHH
MCP6S21-I/MS
MCP6S21T-I/MS
MCP6S22-I/MS
MCP6S22T-I/MS
MCP6S91-E/MS
MCP6S91T-E/MS
MCP6S92-E/MS
MCP6S92T-E/MS